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Ahn et al.

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(54) **DELAMINATION APPARATUS AND INLINE THERMAL IMAGING SYSTEM**

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B29C 69/00 (2006.01)
B32B 43/00 (2006.01)

(52) **U.S. Cl.**
CPC **B29C 69/006** (2013.01); **B32B 38/10** (2013.01); **B32B 43/006** (2013.01); **B32B 2457/20** (2013.01); **Y10T 156/1132** (2015.01); **Y10T 156/1137** (2015.01); **Y10T 156/1174** (2015.01); **Y10T 156/195** (2015.01); **Y10T 156/1939** (2015.01); **Y10T 156/1956** (2015.01); **Y10T 156/1978** (2015.01)

(58) **Field of Classification Search**

CPC B32B 38/10; B32B 43/006; B32N 43/006; Y10T 156/1132; Y10T 156/1174; Y10T 156/1944; Y10T 156/1989; Y10T 156/1137; Y10T 156/1939; Y10T 156/195; Y10T 156/1978
USPC 156/759, 764, 714, 715, 707, 756
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,880,488	A *	11/1989	Matsuo et al.	156/702
5,891,298	A *	4/1999	Kuroda et al.	156/716
7,798,195	B2 *	9/2010	Kobayashi et al.	156/758
8,052,824	B2	11/2011	Kanazawa	
8,052,835	B2 *	11/2011	Merrill et al.	156/707
8,110,069	B2	2/2012	Garben	
8,142,595	B2	3/2012	Kobayashi	

(Continued)

FOREIGN PATENT DOCUMENTS

JP	10-010751	1/1998
JP	2003-136595	5/2003

(Continued)

Primary Examiner — Philip Tucker

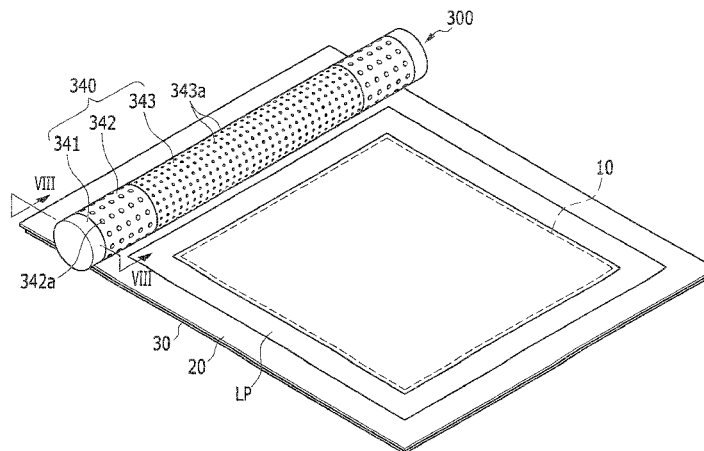
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(57) **ABSTRACT**

A delamination apparatus that includes a stage to which a lower support, an acceptor substrate disposed on the lower support, and a donor film laminated with the lower support along the edge of the acceptor substrate, interposing the acceptor substrate therebetween are mounted. The delamination apparatus further includes a first gripper disposed in an end side of the stage to move an end of the donor film to a direction far away from the acceptor substrate by gripping the end of the donor film; and a first peeling roll disposed on the donor film to support the donor film disposed between the acceptor substrate and the first gripper, and rotating itself to a direction of the first gripper.

20 Claims, 10 Drawing Sheets



(56)

References Cited

2013/0186574 A1 * 7/2013 Baker et al. 156/707

U.S. PATENT DOCUMENTS

8,151,856 B2 4/2012 Kawashima et al.
 2001/0017189 A1 * 8/2001 Tsujimoto et al. 156/344
 2007/0235131 A1 * 10/2007 Tsujimoto et al. 156/344
 2008/0185100 A1 * 8/2008 Jang et al. 156/344
 2009/0288760 A1 * 11/2009 Garben 156/230
 2013/0048223 A1 * 2/2013 Ahn 156/718

FOREIGN PATENT DOCUMENTS

KR 10-2002-0084485 11/2002
 KR 10-2007-0112078 11/2007
 KR 10-2008-0066759 7/2008

* cited by examiner

FIG. 1

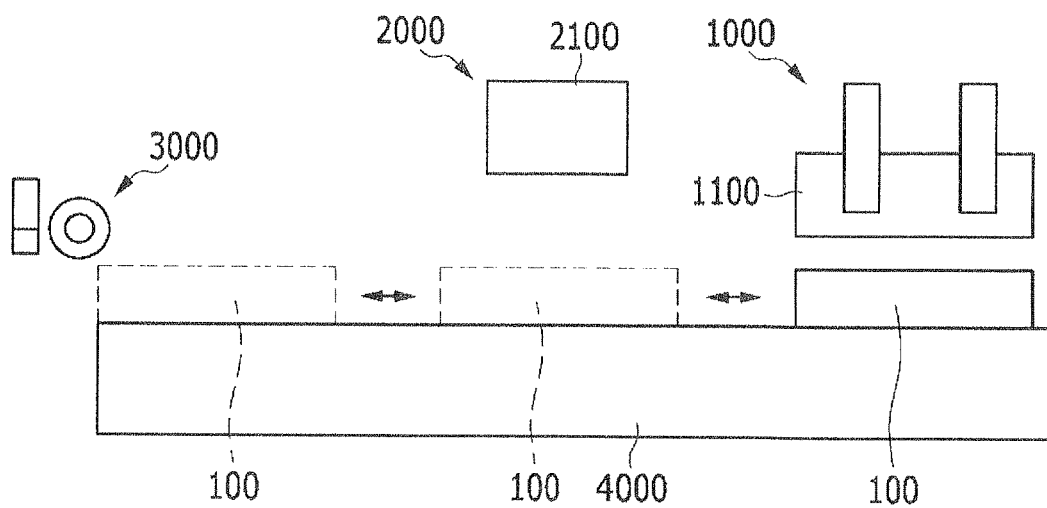


FIG. 2

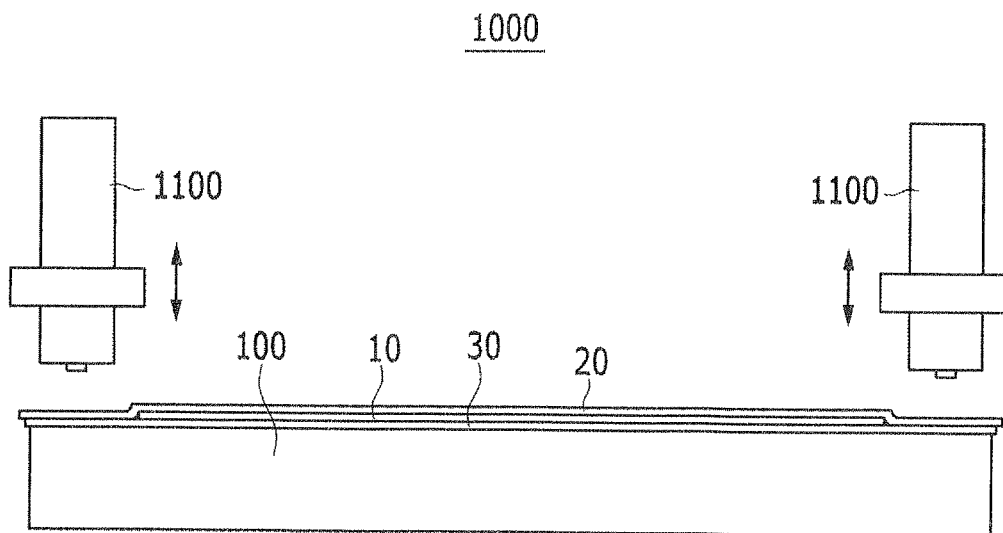


FIG. 3

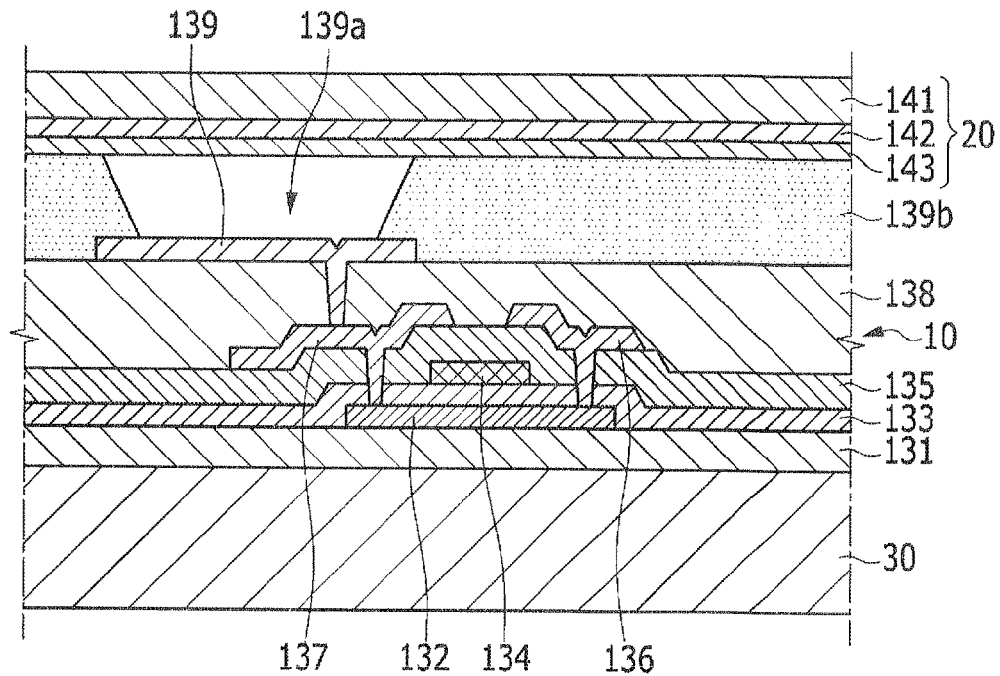


FIG. 4

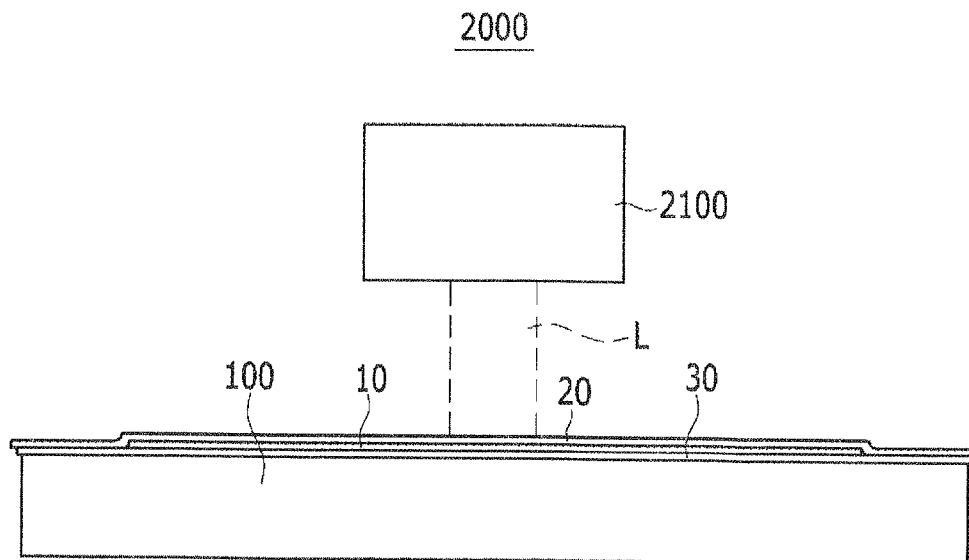


FIG. 5

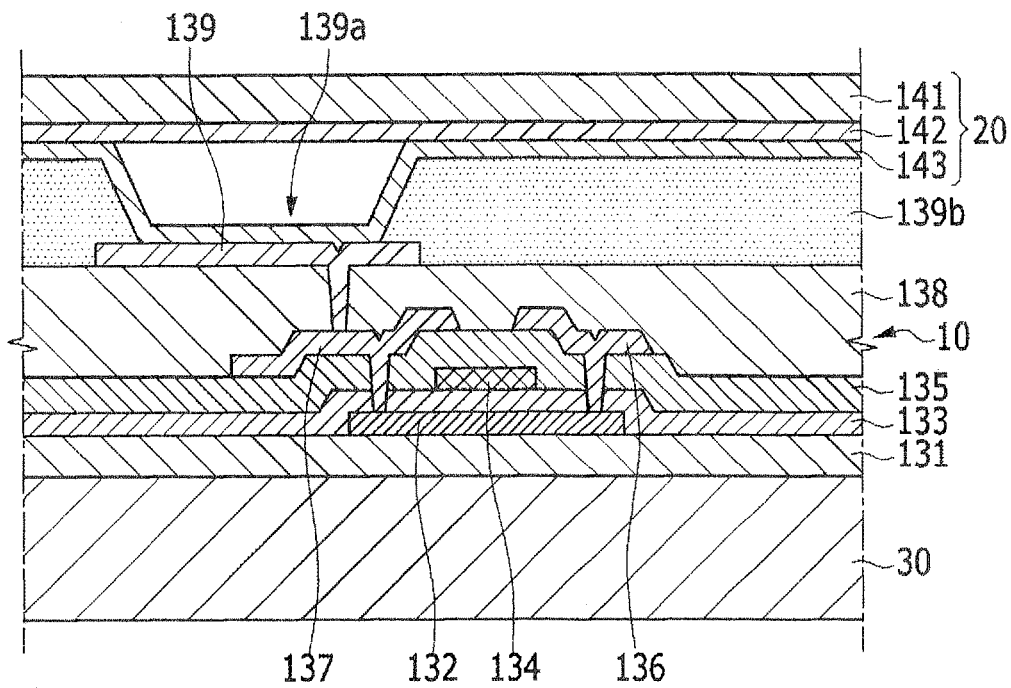


FIG. 6

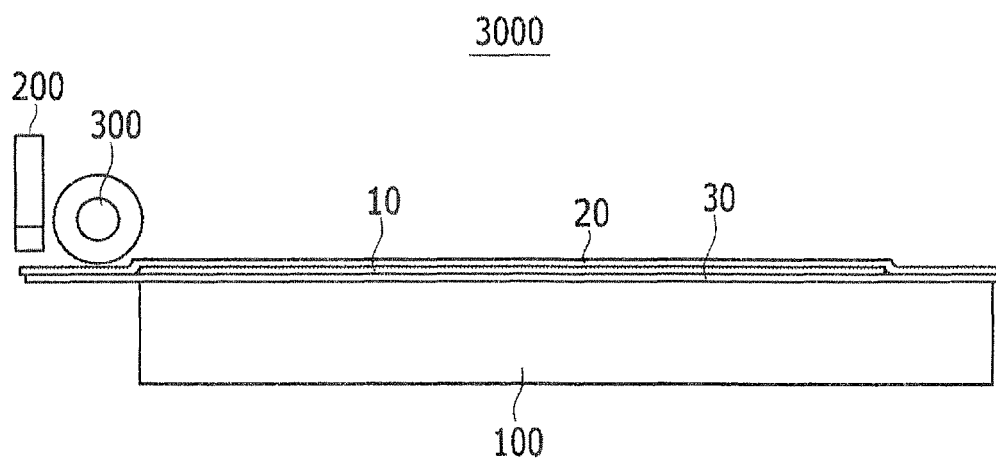


FIG. 7

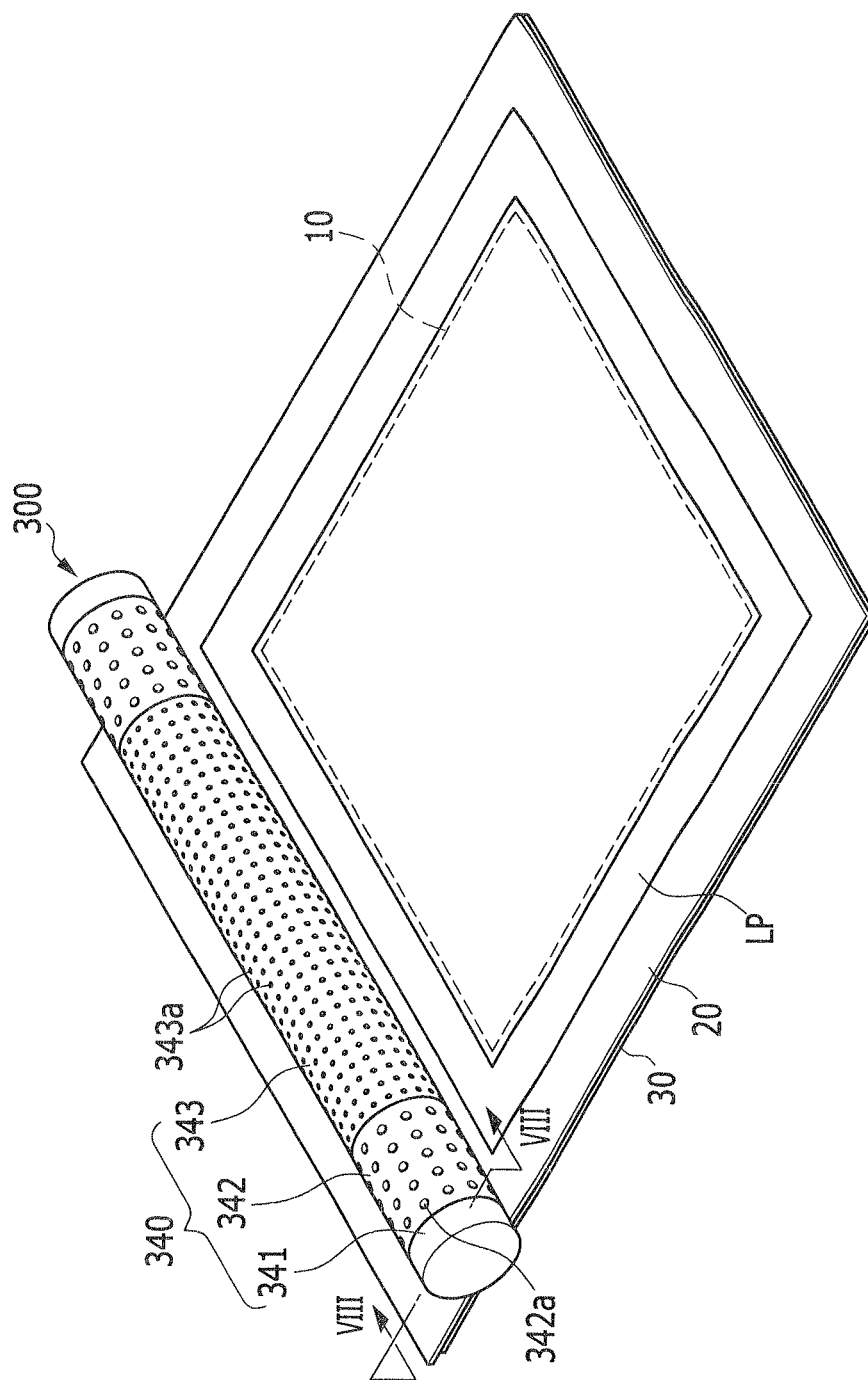


FIG. 8

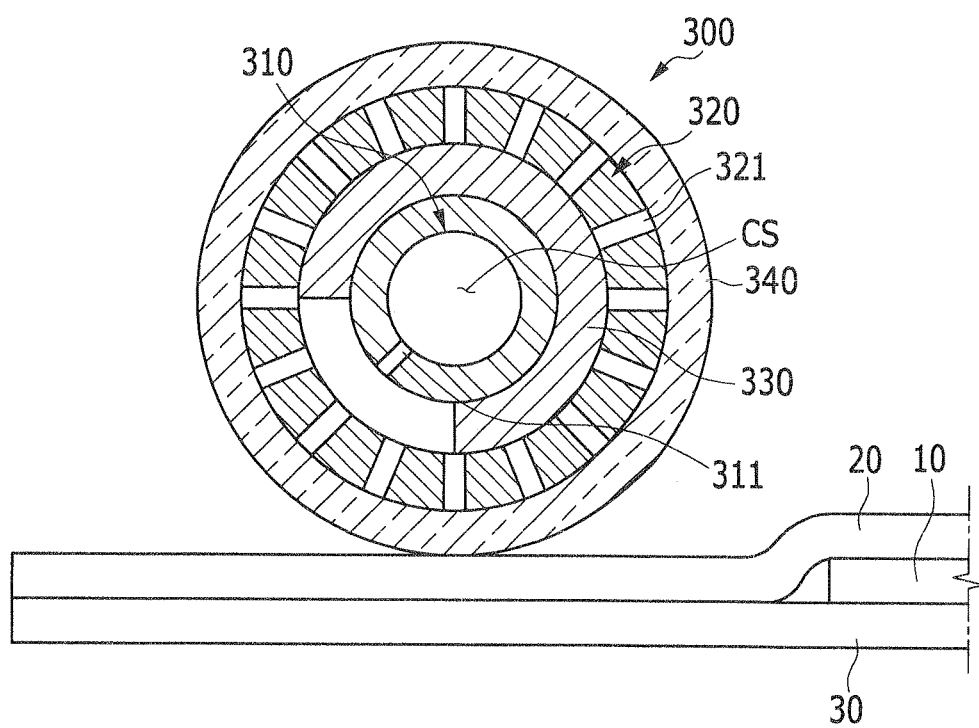


FIG. 9

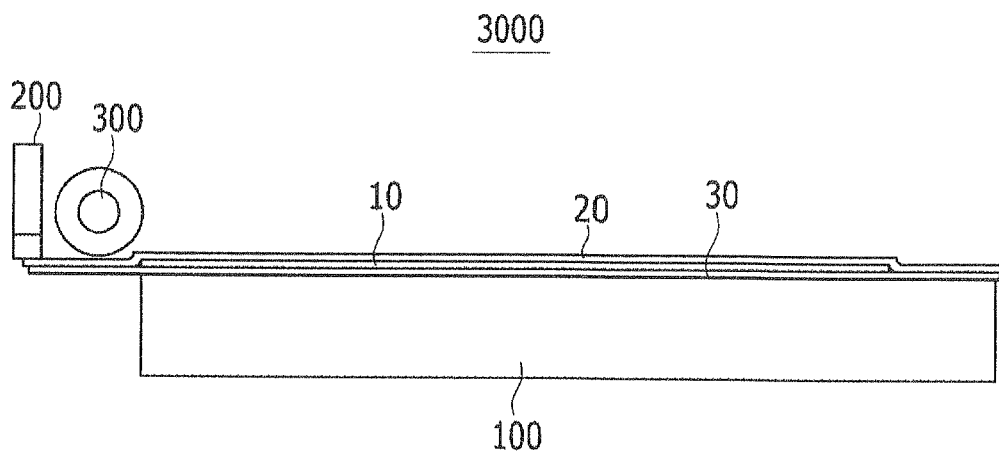


FIG. 10

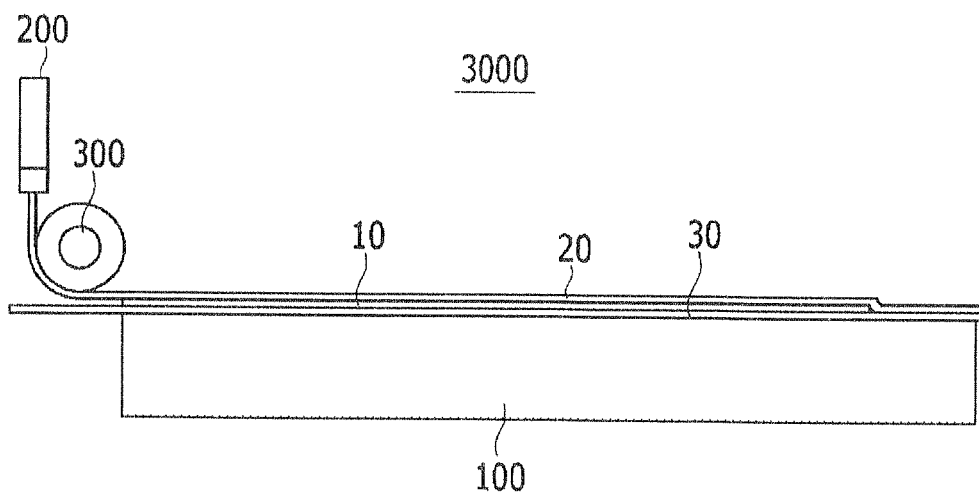


FIG. 11

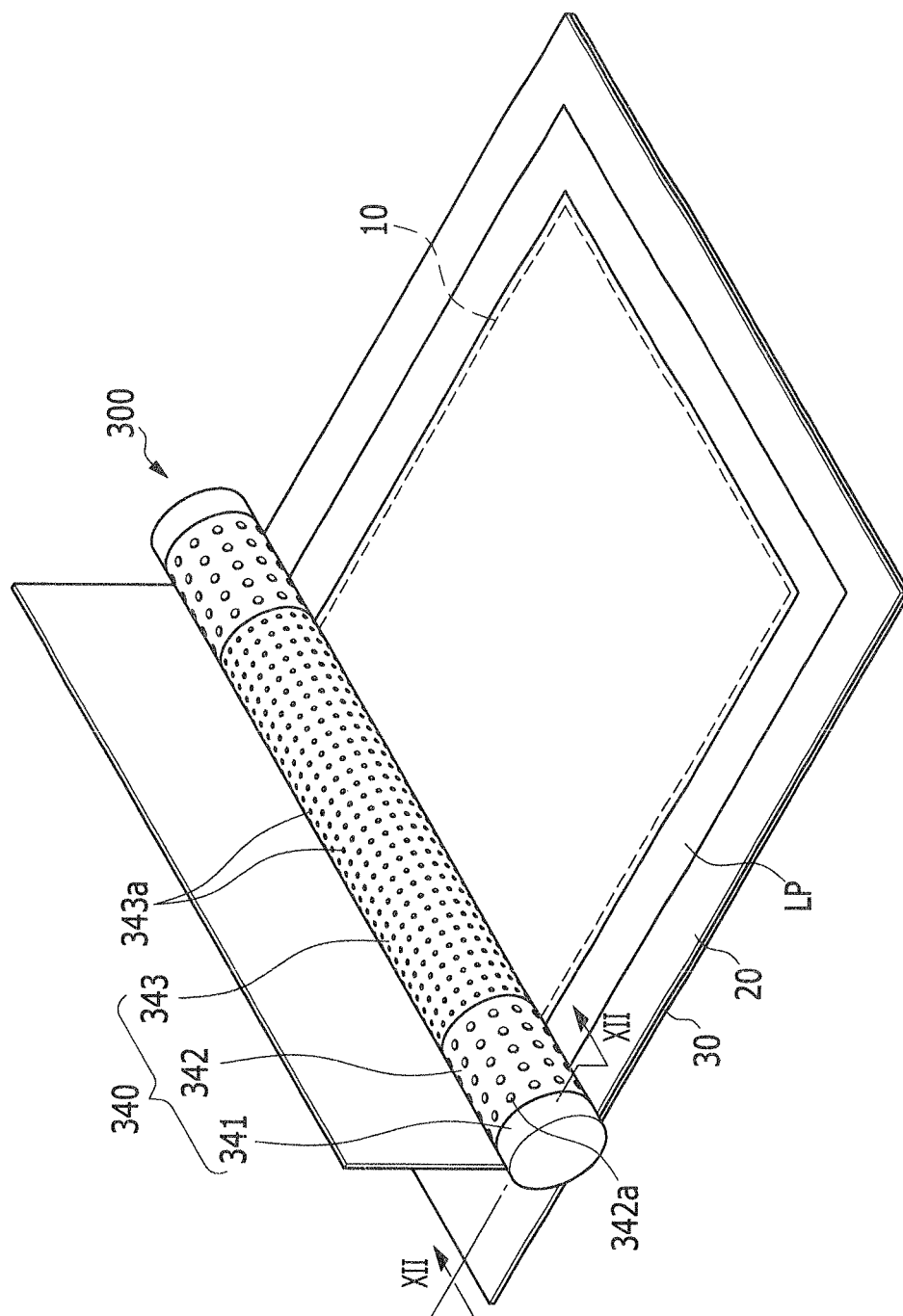


FIG. 12

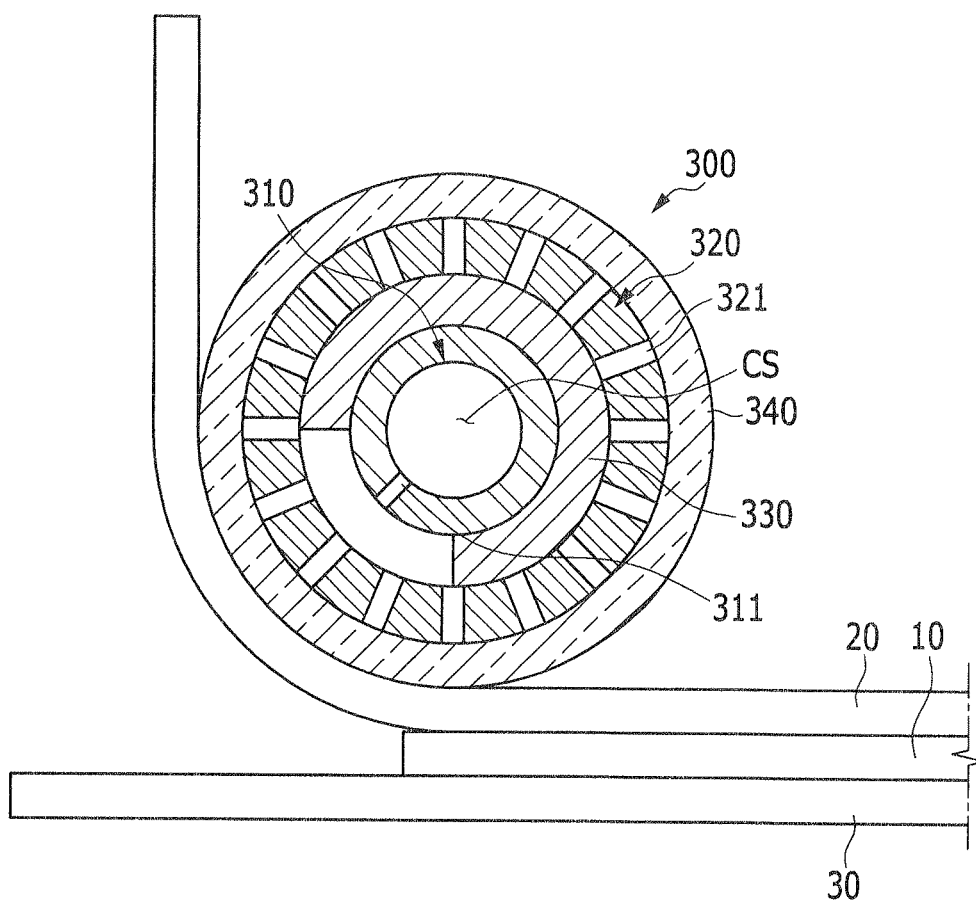


FIG. 13

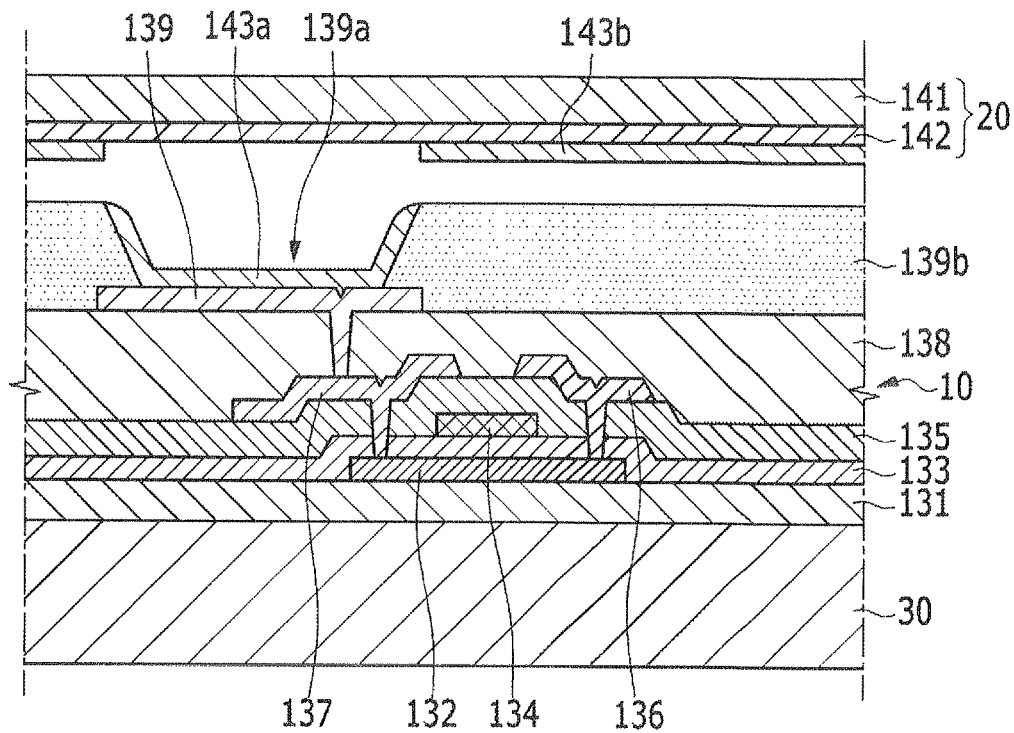


FIG. 14

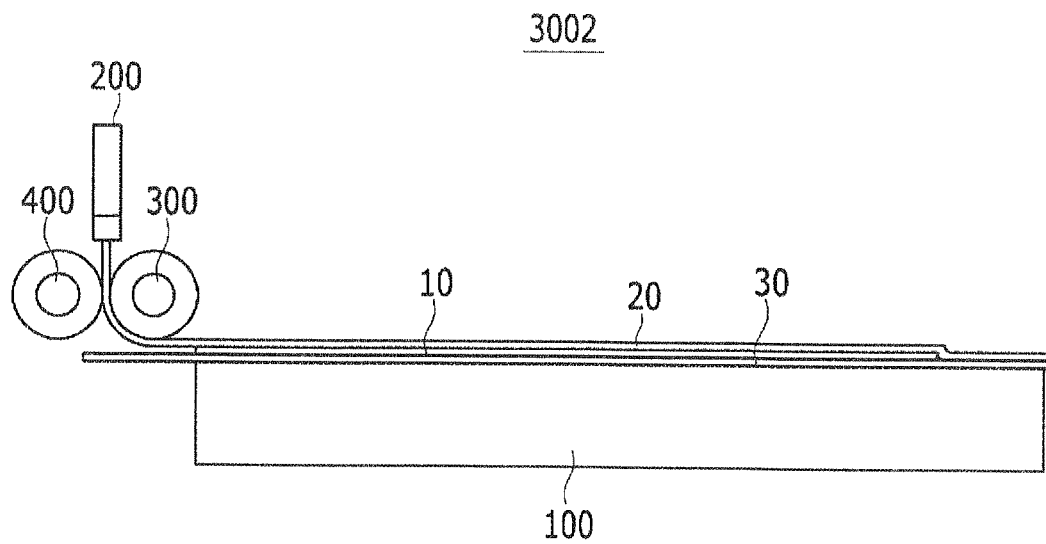


FIG. 15

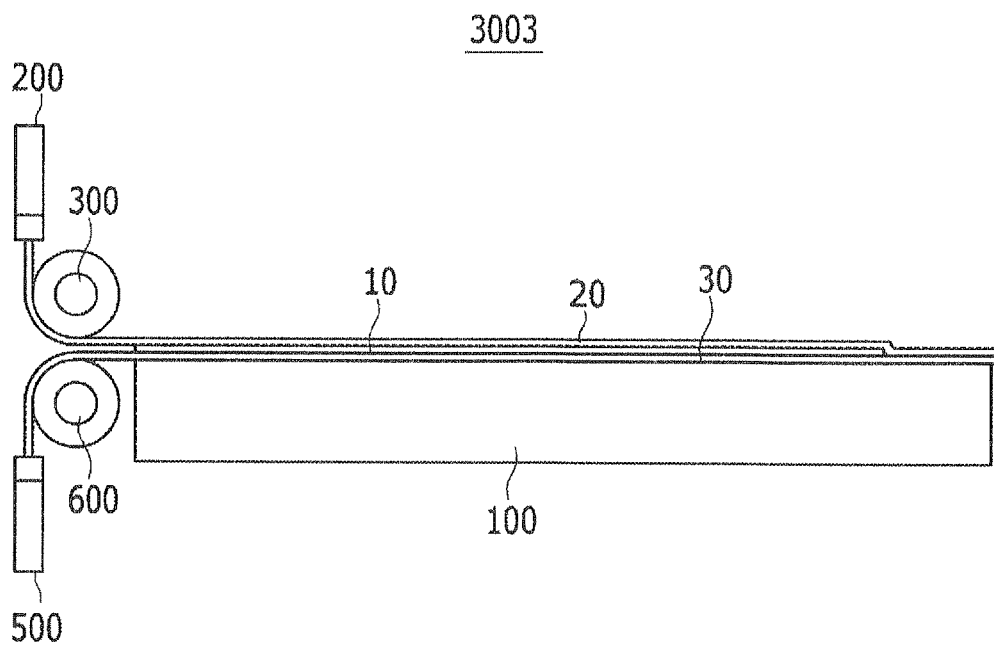
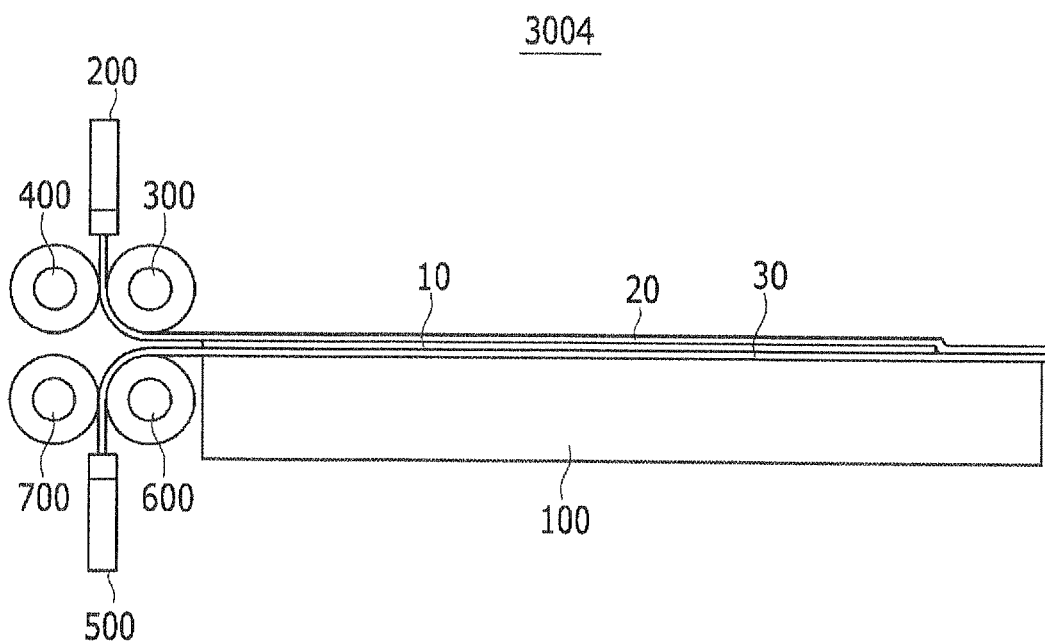


FIG. 16



1

DELAMINATION APPARATUS AND INLINE THERMAL IMAGING SYSTEM

CLAIM OF PRIORITY

This application makes reference to, incorporates the same herein, and claims all benefits accruing under 35 U.S.C. §119 from an application earlier filed in the Korean Intellectual Property Office on the 9 Jul. 2012 and there duly assigned Ser. No. 10-2012-0074639.

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention generally relates to a delamination apparatus and an inline thermal imaging system including the same.

2. Description of the Related Art

An organic light emitting element is a flat display device. Such an organic light emitting element may include an anode, a cathode, and at least organic emission layer interleaved between the anode and the cathode. The organic light emitting element has merits of a wide viewing angle and a superior contrast as well as a fast response speed. Due to the merits of the organic light emitting element, the organic light emitting element has been receiving attention as the next generation display element.

The above information disclosed in this Related Art section is only for enhancement of understanding of the background of the invention and therefore it may contain information that does not form the prior art that is already known in this country to a person of ordinary skill in the art.

SUMMARY OF THE INVENTION

The present invention has been made in an effort to provide a delamination apparatus that can minimize a failure occurring during a delamination process used in a thermal imaging method, and an inline thermal imaging system including the same.

One aspect of the present invention provides a delamination apparatus including: a stage to which a lower support, an acceptor substrate disposed on the lower support, and a donor film laminated with the lower support along the edge of the acceptor substrate, interposing the acceptor substrate therebetween are mounted; a first gripper disposed in an end side of the stage to move an end of the donor to a direction far away from the acceptor substrate by gripping the end of the donor film; and a first peeling roll disposed on the donor film to support the donor film disposed between the acceptor substrate and the first gripper, and rotating itself to a direction of the first gripper.

The first peeling roll may include: a fixing shaft through which air passes, and including a first slit penetrated to a direction between the acceptor substrate and the first gripper from the inside of the fixing shaft; an external roll surrounding the fixing shaft, rotating itself with respect to the fixing shaft, and including a plurality of second slits disposed along an outer part and penetrated to a direction of the fixing shaft; and a barrier supported by the fixing shaft and disposed between the fixing shaft and the external roll, and opening a direction between the acceptor substrate and the first gripper.

The barrier may open a ¼ area of the entire outer part of the fixing shaft.

The air may move from the first slit to the second slit.

The air may move from the second slit to the first slit.

2

The first peeling roll may further include a cover surrounding the external roll.

The cover may include: a first sub-cover disposed corresponding to the end of the donor film and blocking the second slit; a second sub-cover disposed adjacent to the first sub-cover corresponding to a portion of the donor film laminated with the lower support, and including a plurality of first penetration holes; and a third sub-cover disposed adjacent to the second sub-cover corresponding to the acceptor substrate and including a plurality of second penetration holes that are smaller than the first penetration holes in size.

The delamination apparatus may further include a first support roll disposed opposite to the first peeling roll, interposing the donor film therebetween.

The delamination apparatus may further include: a second gripper disposed in an end side of the stage to grip an end of the lower support, and moving the end of the lower support to a direction far away from the acceptor substrate; and a second peeling roll disposed on the lower support to support the lower support disposed between the acceptor substrate and the second gripper, and rotating itself to a direction of the second gripper.

The delamination apparatus may further include a second support roll disposed opposite to the second peeling roll, interposing the lower support therebetween.

Another aspect of the present invention provides an inline thermal imaging system including: the delamination apparatus as described above; a transferring apparatus neighboring the delamination apparatus, and including a laser unit irradiating laser beams to the donor film corresponding to the acceptor substrate; a lamination apparatus neighboring the transferring apparatus, and including a lamination unit laminating the donor film to the lower support, interposing the acceptor substrate therebetween; and a stage movement apparatus respectively moving the stage to the lamination apparatus, the transferring apparatus, and the delamination apparatus.

According to the exemplary embodiments of the present invention, a delamination apparatus and an inline thermal imaging system having the same may minimize defect generated during a delamination process using a thermal imaging method.

BRIEF DESCRIPTION OF THE DRAWINGS

A more complete appreciation of the invention, and many of the attendant advantages thereof, will be readily apparent as the same becomes better understood by reference to the following detailed description when considered in conjunction with the accompanying drawings, in which like reference symbols indicate the same or similar components, wherein:

FIG. 1 shows an inline thermal imaging system according to a first exemplary embodiment of the present invention.

FIG. 2 shows a lamination apparatus shown in FIG. 1.

FIG. 3 is a cross-sectional view of an acceptor substrate laminated with a donor film using the lamination apparatus shown in FIG. 2.

FIG. 4 shows the transferring apparatus shown in FIG. 1.

FIG. 5 is a cross-sectional view of an acceptor substrate to which an organic layer of the donor film is transferred using the transferring apparatus shown in FIG. 4.

FIG. 6 through FIG. 8 illustrate a delamination apparatus shown in FIG. 1.

FIG. 9 through FIG. 12 are provided for description of a delamination process using the delamination apparatus shown in FIG. 8.

3

FIG. 13 is a cross-sectional view of an acceptor substrate delaminated with a donor film through the delamination process shown in FIG. 9 to FIG. 12.

FIG. 14 shows a delamination apparatus according to a second exemplary embodiment of the present invention.

FIG. 15 shows a delamination apparatus according to a third exemplary embodiment of the present invention.

FIG. 16 shows a delamination apparatus according to a fourth exemplary embodiment of the present invention.

DETAILED DESCRIPTION OF THE INVENTION

In the following detailed description, only certain exemplary embodiments of the present invention have been shown and described, simply by way of illustration. As those skilled in the art would realize, the described embodiments may be modified in various different ways, all without departing from the spirit or scope of the present invention.

Accordingly, the drawings and description are to be regarded as illustrative in nature and not restrictive. Like reference numerals designate like elements throughout the specification.

For various exemplary embodiments, constituent elements having the same constitution are designated to the same reference numerals and explained representatively in the first exemplary embodiment. In the other exemplary embodiments, only the constituent elements different from in the first exemplary embodiment are described.

In drawings, a size and a thickness of each element is approximately shown for better understanding and ease of description. Therefore, the present invention is not limited to the drawings.

In the drawings, the thickness of layers, films, panels, regions, etc., are exaggerated for clarity. In drawings, a size and a thickness of each element are exaggerated for better understanding and ease of description. It will be understood that when an element such as a layer, film, region, or substrate is referred to as being "on" another element, it can be directly on the other element or intervening elements may also be present.

In addition, unless explicitly described to the contrary, the word "comprise" and variations such as "comprises" or "comprising" will be understood to imply the inclusion of stated elements but not the exclusion of any other elements. It will be understood that when an element such as a layer, film, region, or substrate is referred to as being "on" another element, it can be on the other element or under the other element. The element may not be on another element in a gravity direction.

Generally, an organic light emitting element may include at least one of organic layers interleaved among a hole injection layer (HIL), a hole transport layer (ETL), and an electron injection layer (EIL) according to whether an emission layer is made of a high molecular organic material or a low molecular organic material besides an organic emission layer.

In such an organic light emitting element, an organic layer may be required to be patterned in order to realize full color. A low molecular organic light emitting element may be patterned using a shadow mask, and a high molecular organic light emitting element may be patterned through an ink-jet printing method and a laser induced thermal imaging (LITI) method using laser. The LITI method may be advantageous because the LITI method can pattern a large area of an organic layer. Furthermore, the LITI method can pattern an organic layer with high precision and with high resolution.

4

Hereinafter, an inline thermal imaging system according to a first exemplary embodiment of the present invention will be described with reference to FIG. 1 to FIG. 13.

FIG. 1 shows an inline thermal imaging system according to the first exemplary embodiment of the present invention.

As shown in FIG. 1, the inline thermal imaging system according to the first exemplary embodiment of the present invention is an inline system that laminates a donor film to an acceptor substrate, transfers an organic layer formed in the donor film by irradiating laser beams, and delaminates the donor film from the acceptor substrate, and includes a lamination apparatus 1000, a transferring apparatus 2000, a delamination apparatus 3000, and a stage moving apparatus 4000. The stage moving apparatus 4000 moves stages 100 to which the acceptor substrate may be mounted respectively to the lamination apparatus 1000, the transferring apparatus 2000, and the delamination apparatus 3000, and may include a moving means such as a rail and the like and a driving means such as a motor and the like to drive the moving means. The stages 100 moved by the stage moving apparatus 4000 are respectively included in the lamination apparatus 1000, the transferring apparatus 2000, and the delamination apparatus 3000.

FIG. 2 shows the lamination apparatus shown in FIG. 1.

As shown in FIG. 2, the lamination apparatus 1000 is an apparatus for laminating the donor film 20 to the acceptor substrate 10, and includes the stage 100 and a lamination unit 1100.

A lower support 30 formed in the shape of a film, an acceptor substrate 10 disposed on the lower support 30, and the donor film 20 laminated with the lower support 30 along the edge of the acceptor substrate 10, interposing the acceptor substrate 10 are mounted to the stage 100. The stage 100 may include a stage align key that corresponds to an align key formed in the acceptor substrate 10.

The lamination unit 1100 may be movable to up and down with respect to the stage 100 and maintains an area where the acceptor substrate 10 may be located in a vacuum state, and then adheres the donor film 20 and the lower support 30 using heat and the like along the edge of the acceptor substrate 10 of the stage 100. Accordingly, the lower support 30 and the donor film 20 are laminated, interposing the acceptor substrate 10 therebetween, and the acceptor substrate 10 may be sealed between the donor film 20 and the lower support 30. Here, the lower support 30 may be disposed between the stage 100 and the acceptor substrate 10 and between the stage 100 and the donor film 20.

In the first exemplary embodiment of the present invention, the lower support 30 may be disposed between the stage 100 and the acceptor substrate 10 and between the stage 100 and the donor film 20, but when a lower support 30 is omitted in another exemplary embodiment of the present invention, a donor film 20 may be directly bonded with a stage 100 along the edge of an acceptor substrate 10.

Hereinafter, the acceptor substrate 10 laminated with the donor film 20 will be described.

FIG. 3 is a cross-sectional view of the acceptor substrate laminated with the donor film using the lamination apparatus shown in FIG. 2.

As shown in FIG. 3, in the acceptor substrate 10, a semiconductor layer 132 may be disposed in a predetermined area on a substrate 131. The semiconductor layer 132 may be an amorphous silicon layer or a polysilicon layer crystallized from the amorphous silicon layer. A gate insulating layer 133 that is a first insulating layer may be disposed on the semiconductor layer 132. A gate electrode 134 overlapping the semiconductor layer 132 may be disposed on the gate insulating layer 133.

5

lating layer **133**. A second insulating layer **135** covering the semiconductor layer **132** and the gate electrode **134** may be disposed on the gate electrode **134**. A source electrode **136** and a drain electrode **137** respectively connecting lateral ends of the semiconductor layer **132** penetrating the second insulating layer **135** and the first insulating layer **133** are disposed on the second insulating layer **135**. The semiconductor layer **132**, the gate electrode **134**, and the source/drain electrodes **136** and **137** form a thin film transistor T. A third insulating layer **138** covering the source/drain electrodes **136** and **137** may be disposed on the source/drain electrodes **136** and **137**. The third insulating layer **138** may be a passivation layer for protecting the thin film transistor T and/or a planarization layer for reducing a step difference due to the thin film transistor. A pixel electrode **139** connected with the drain electrode **137** may be disposed on the third insulating layer **138** while penetrating the third insulating layer **138**. The pixel electrode **139** may be, for example, an indium tin oxide (ITO) layer or an indium zinc oxide (TIO) layer. A pixel defining layer **139b** having an opening that partially exposes the pixel electrode **139** may be disposed on the pixel electrode **139**.

The donor film **20** laminated on the acceptor substrate **10** may include a base film **141**, a light to heat conversion layer **142**, and an organic layer **143**. The light to heat conversion layer **142** and the organic layer **143** may be sequentially stacked on one side of the base film **141**. The donor film **20** may have a predetermined elasticity. The based film **141** may be made of a transparent high molecular organic material such as polyethylene terephthalate (PET), Polyethylene naphthalate (PEN), polyethylene (PE), and polycarbonate (PC). The light to heat conversion layer **142** may convert an incident light, which is laser, to heat. The light to heat conversion layer **142** may include light absorption material such as aluminum oxide, aluminum sulfide, carbon black, graphite or infrared ray dye. The organic layer **143** may be at least one selected from the group consisting of a hole injection layer (HIL), a hole transport layer (HTL), an electro-luminescence layer, a hole suppress layer, an electron transport layer (ETL), and an electron injection layer (EIL).

FIG. 4 illustrates a transferring apparatus of FIG. 1.

As shown in FIG. 4, the transferring apparatus **2000** may be disposed between the lamination apparatus **1000** and the delamination apparatus **3000**. The transferring apparatus **2000** may transport an organic layer of the donor film **20** laminated at the acceptor substrate **10** on the acceptor substrate **10**. The transport apparatus **2000** may include a stage **100** and a laser unit **2100**.

The laser unit **2100** may radiate laser L at the donor film **20** corresponding to a substrate area SA of the stage **100**. Due to the laser L, the organic layer **143** formed on the donor film **20** may be transferred to the acceptor substrate **10**. The laser L may be radiated to the donor film **20** corresponding to an opening **139a** of the acceptor substrate **10**.

The transferring apparatus **2000** may include a thermal imaging unit instead of the laser unit **2100**, and in this case, the thermal imaging unit may transfer the organic layer **143** formed in the donor film **20** to the acceptor substrate **10** by applying heat to the donor film **20**.

Hereinafter, the acceptor substrate **10** where the organic layer **143** of the donor film **20** may be transferred will be described.

FIG. 5 is a cross-sectional view illustrating an acceptor substrate having an organic layer of a donor film transferred using a transport apparatus of FIG. 4.

As shown in FIG. 5, the organic layer **143** may be transferred to the acceptor substrate **10** corresponding to an opening **139a** of the acceptor substrate **10**.

6

FIG. 6 to FIG. 8 illustrate a delamination apparatus of FIG. 1.

As shown in FIG. 6, the delamination apparatus **3000** may be adjacent to the transferring apparatus **2000**. The delamination apparatus **3000** delaminates the donor film **20** from the acceptor substrate **10** where the organic layer **143** may be transferred. The delamination apparatus **3000** includes a stage **100**, a first gripper **200**, and a first peeling roll **300**.

The first gripper **200** may be disposed in an end side of the stage **100**, and grips the end of the donor film **20**. The first gripper **200** moves the donor film **20** to a direction far away from the acceptor substrate **10**, for example, an upper side by gripping the end of the donor film **20** to separate the end of the donor film **20** from the lower support **30**. When the first gripper **200** separates the end of the donor film **20** from the lower support **30**, the donor film **20** contacts the first peeling roll **300**.

FIG. 7 shows the first peeling roll, the lower support, the acceptor substrate, and the donor film shown in FIG. 6. FIG. 8 is a cross-sectional view of FIG. 7, taken along the line VIII-VIII.

As shown in FIG. 6 to FIG. 8, the first peeling roll **300** may be disposed on the donor film **20**. The first peeling roll **300** supports the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200**. Here, the supporting of the donor film **20** implies suction or blowing the donor film **20**.

The first peeling roll **300** rotates itself to a direction of the first gripper **200**. For example, the first peeling roll **300** rotates in a clockwise direction to delaminate the donor **20** from the lower support **30**.

The first peeling roll **300** includes a fixing shaft **310**, an external roll **320**, a barrier **330**, and a cover **340**.

The fixing shaft **310** includes a connection space CS through which air such as nitrogen (N) or oxygen (O) and a first slit **311** penetrated to a direction between the acceptor substrate **10** and the first gripper **200** from the inside of the connection space CS. The fixing shaft **310** may be disposed in the fixed stated on the donor film **20**, and does not rotate.

An external roll **320** surrounds the fixing shaft **310**, and rotates with respect to the fixing shaft **310**. The external roll **320** includes a plurality of second slits **321** disposed along the outer part and penetrated to the fixing shaft **310**. A bearing may be provided between the external roll **320** and the fixing shaft **310**, and the first peeling roll **300** rotates by itself as the external roll **320** rotates by itself.

The barrier **330** supported by the fixing shaft **310** may be disposed between the fixing shaft **310** and the external roll **320**, and opens a direction between the acceptor substrate **10** and the first gripper **200**. The barrier **330** opens a $\frac{1}{4}$ area of the entire area surrounding the outer part of the fixing shaft **310**. For example, the barrier **330** opens an area rotated 90 degrees from a direction that may be perpendicular to the plate surface of the donor film **20**.

The air passes through the connection space CS may move to a direction of the first slit **311** direction from the second slit **321** or may move to a direction of the second slit **321** from the first slit **311**. When the air passing through the connection space CS moves to the first slit **311** direction from the second slit **321**, the first peeling roll **300** sucks the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200** to support the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200**. In addition, when the air passing through the connection space CS moves to the second slit **321** direction from the first slit **311**, the first peeling roll **300** forms an air layer between the first peeling roll **300** and the donor film **20** by blowing the donor film **20**.

disposed between the acceptor substrate **10** and the first gripper **200** to support the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200**.

The cover **340** surrounds the external roll **320**, and includes first sub-cover **341**, a second sub-cover **342**, and a third sub-cover **343**.

The first sub-cover **341** may be disposed corresponding to an end of the donor film **20** and blocks the second slit **321** of the external roll **320**.

The second sub-cover **342** may be adjacent to the first sub-cover **341** and disposed corresponding to a portion LP of the donor film **20** laminated with the lower support **30**. The second sub-cover **342** includes a plurality of first penetration holes **342a** formed along the outer part. The air passing through the connection space CS of the fixing shaft **310** passes through the first slit **311**, the second slit **321**, and the first penetration hole **342a**.

The third sub-cover **343** may be adjacent to the second sub-cover **342** and disposed corresponding to the acceptor substrate **10**. The third sub-cover **343** includes a plurality of second penetration holes **343a** formed along the outer part. The second penetration hole **343a** is formed smaller than the first penetration hole **342a** in size. The air passed through the connection space CS of the fixing shaft **310** passes through the first slit **311**, the second slit **321**, and the second penetration hole **343a**.

Hereinafter, a delamination process using the delamination apparatus **3000** will be described in further detail with reference to FIG. 9 through FIG. 12.

FIG. 9 to FIG. 12 are provided for description of a delamination process using the delamination apparatus of FIG. 6 to FIG. 8.

First, as shown in FIG. 9, the end of the donor film **20** may be gripped using the first gripper **200**. In this case, the first peeling roll **300** may be disposed on the donor film **20**, and may contact the donor film **20** or may be separated from the donor film **20**.

Next, as shown in FIG. 10, the first gripper **200** may be moved to an upper side to separate the end of the donor film **20** from the lower support **30** such that the donor film **20** may be supported by the first peeling roll **300**.

FIG. 11 shows the first peeling roll, the lower support, the acceptor substrate, and the donor film shown in FIG. 10. FIG. 12 is a cross-sectional view of FIG. 11, taken along the line XII-XII.

Next, as shown in FIG. 11 and FIG. 12, the first peeling roll **300** rotates itself and thus the donor film **20** may be delaminated from the lower support **30**.

In further detail, since the air is sucked or blown to the direction between the acceptor substrate **10** and the first gripper **200** while the external roll **320** rotates with respect to the fixing shaft **310** that is in the fixed state, the first peeling roll **300** rotates itself while the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200** is supported by the first peeling roll **300** so that the donor film **20** may be delaminated from the lower support **30**.

In this case, the end of the donor film **20** may be pressed by the first sub-cover **341** corresponding to the first sub-cover **341** that blocks the second slit **321** of the external roll **320** so that the end of the donor film **20** can be prevented from being lifted due to suction or blowing of the first peeling roll **300**. Thus, particles that can be generated due to separation of the donor film **20** from the lower support **30** or external air can be prevented from being penetrated into the acceptor substrate **10** disposed between the donor film **20** and the lower support **30**.

In addition, since the portion LP of the donor film **20** laminated with the lower support **30** may be supported by the first peeling roll **300** corresponding to the second sub-cover **342** including the first penetrating hole **342a** formed larger than the second penetrating hole **343a** in size, suction or blowing is locally performed with high pressure so that the delamination from the lower support **30** can be easily performed.

In addition, the center area of the donor film **20** corresponding to the acceptor substrate **10** may be supported by the first peeling roll **300** corresponding to the third sub-cover **343** including the second penetration hole **343a** formed smaller than the first penetration hole **342a** so that suction or blowing is locally performed with low pressure, thereby suppressing a failure in the acceptor substrate **10** that may be occurred from delamination of the donor film **20** from the lower support **30**.

As described, the first peeling roll **300** supports the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200** rather than supporting the donor film **20** disposed between the acceptor substrate **10** and the first peeling roll **300** to delaminate the donor film **20** from the lower support **30**, and accordingly a failure that may occur in the acceptor substrate **10** due to suction or blowing of the first peeling roll **300** can be originally prevented.

Further, the first peeling roll **300** supports the donor film **20** by sucking or blowing the donor film **20** so that the donor film **20** can be prevented from being separated from the first peeling roll **300**. This can be a factor for improvement of reliability of the entire delamination process.

Hereinafter, the acceptor substrate **10** through which the donor film **20** is delaminated will be described.

FIG. 13 is a cross-sectional view of the acceptor substrate from which the donor film may be delaminated through the delamination process shown in FIG. 9 to FIG. 12.

As shown in FIG. 13, since the donor film **20** may be separated from the acceptor substrate **10**, an organic layer **143a** transferred corresponding to the opening **139a** of the acceptor substrate **10** may be separated from an organic layer **143b** remaining in the donor film **20**, and the organic layer **143a** functions as a light emission means of an organic light emitting element.

As described above, the inline thermal imaging system according to the first exemplary embodiment of the present invention may include the lamination apparatus **1000**, the transport apparatus **2000**, and the delamination apparatus **3000**, which share the stage **100**. The inline thermal imaging system according to the first exemplary embodiment of the present invention may perform the lamination process, the imaging process, and the delamination process in an inline manner.

Furthermore, the inline thermal imaging system according to the first exemplary embodiment of the present invention perform the lamination process, the imaging process, and the delamination process using one stage **100**. The lamination process, the imaging process, and the delamination process can be performed without the lower support **30** by directly attaching the donor film **20** at the stage **100** to seal the acceptor substrate **10**. Accordingly, a manufacturing time and a manufacturing cost can be reduced.

Hereinafter, a delamination apparatus according to a second exemplary embodiment of the present invention will be described with reference to FIG. 14.

As compared to the delamination apparatus according to the first embodiment, only distinguishing elements of the delamination apparatus according to the second embodiment will be described. Since the remaining elements of the delamination apparatus according to the second embodiment

have the similar configuration, the detailed description thereof will be omitted herein. For better comprehension and ease of description, identical constituent elements between the first embodiment and the second embodiment will be described using the same reference numerals.

FIG. 14 illustrates a delamination apparatus in accordance with the second exemplary embodiment of the present invention.

As shown in FIG. 14, a delamination apparatus **3002** according to the second exemplary embodiment of the present invention further includes a first support roll **400**.

The first support roll **400** may be disposed opposite to a first peeling roll **300**, interposing a donor film **20** therebetween, and the donor film **20** may be supported between the first peeling roll **300** and the first support roll **400** when the donor film **20** may be delaminated from a lower support **30**.

Like the first peeling roll **300** of the first exemplary embodiment, the first support roll **400** may include a fixing shaft, an external roll, a barrier, and a cover, and the fixing shaft, the external roll, the barrier, and the cover included in the first support roll **400** may be the same as the fixing shaft **310**, the external roll **320**, the barrier **330**, and the cover **340** included in the first peeling roll **300**.

As described, in the delamination apparatus **3002** according to the second exemplary embodiment of the present invention, the donor film **20** disposed between the acceptor substrate **10** and the first gripper **200** may be supported between the first peeling roll **300** and the first support roll **400** and thus delaminated from a lower support **30** so that a failure that may occur in the acceptor substrate **10** due to suction or blowing by the first peeling roll **300** and the first support roll **400** can be originally prevented.

Hereinafter, a delamination apparatus according to a third exemplary embodiment of the present invention will be described with reference to FIG. 15.

As compared to the delamination apparatus according to the first embodiment, only distinguishing elements of the delamination apparatus according to the third embodiment will be described. Since the remaining elements of the delamination apparatus according to the third embodiment have the similar configuration, the detailed description thereof will be omitted herein. For better comprehension and ease of description, identical constituent elements between the first embodiment and the third embodiment will be described using the same reference numerals.

FIG. 15 shows a delamination apparatus according to the third exemplary embodiment of the present invention.

As shown in FIG. 15, a delamination apparatus **3003** according to the third exemplary embodiment of the present invention further includes a second gripper **500** and a second peeling roll **600**.

The second gripper **500** may be disposed in an end side of a stage **100** to grip an end of a lower support **30**. The second gripper **500** moves the end of the lower support **30** to a direction far away from an acceptor substrate **10**, for example, to a lower side by gripping the end of the lower support **30** so that the end of the lower support **30** may be separated from the acceptor substrate **10**. When the second gripper **500** separates the end of the lower support **30** from the acceptor substrate **10**, the lower support **30** contacts the second peeling roll **600**.

The second peeling roll **600** may be disposed on the lower support **30**. The second peeling roll **600** supports the lower support **30** disposed between the acceptor substrate **10** and the second gripper **500**. Here, the supporting the lower support **30** implies suction or blowing performed on the lower support **30**.

The second peeling roll **600** rotates itself to a direction of the second gripper **500**. For example, the second peeling roll **600** delaminates the lower support **30** from the donor film **20** by being rotated to the counterclockwise direction.

Like the first peeling roll **300**, the second peeling roll **600** may include a fixing shaft, an external roll, a barrier, and a cover, and the fixing shaft, the external roll, the barrier, and the cover included in the second peeling roll **600** may be the same as the fixing shaft **310**, the external roll **320**, the barrier **330**, and the cover **340** included in the first peeling roll **300**.

As described above, in delamination apparatus **3003** according to the third exemplary embodiment of the present invention, the donor film **20** between the acceptor substrate **10** and the first gripper **200** may be supported by the first peeling roll **300** and thus being delaminated from the lower support **30**, and at the same time, the lower support **30** between the acceptor substrate **10** and the second gripper **400** may be supported by the second peeling roll **600** and thus being delaminated from the donor film **20** so the a failure that may occur in the acceptor substrate **10** due to suction or blowing by the first peeling roll **300** and the second peeling roll **600** can be originally prevented.

Hereinafter, a delamination apparatus according to a fourth exemplary embodiment of the present invention will be described with reference to FIG. 16.

As compared to the delamination apparatus according to the first embodiment, only distinguishing elements of the delamination apparatus according to the fourth embodiment will be described. Since the remaining elements of the delamination apparatus according to the fourth embodiment have the similar configuration, the detailed description thereof will be omitted herein. For better comprehension and ease of description, identical constituent elements between the first embodiment and the fourth embodiment will be described using the same reference numerals.

FIG. 16 shows the delamination apparatus according to the fourth exemplary embodiment of the present invention.

As shown in FIG. 16, a delamination apparatus **3004** according to the fourth exemplary embodiment of the present invention further includes a first support roll **400**, a second gripper **500**, a second peeling roll **600**, and a second support roll **700**.

The first support roll **400** may be disposed opposite to a first peeling roll **300**, interposing a donor film **20** therebetween, and the donor film **20** may be supported between the first peeling roll **300** and the first support roll **400** when the donor film **20** may be delaminated from a lower support **30**.

Like the first peeling roll **300**, the first support roll **400** may include a fixing shaft, an external roll, a barrier, and a cover, and the fixing shaft, the external roll, the barrier, and the cover included in the first support roll **400** may be the same as the fixing shaft **310**, the external roll **320**, the barrier **330**, and the cover **340** included in the first peeling roll **300**.

The second gripper **500** may be disposed in an end side of a stage **100** to grip an end of the lower support **30**. The second gripper **500** moves the end of the lower support **30** to a direction far away from an acceptor substrate **10**, for example, to a lower side by gripping the end of the lower support **30** so that the end of the lower support **30** may be separated from the acceptor substrate **10**. When the second gripper **500** separates the end of the lower support **30** from the acceptor substrate **10**, the lower support **30** contacts the second peeling roll **600**.

The second peeling roll **600** may be disposed on the lower support **30**. The second peeling roll **600** supports the lower support **30** disposed between the acceptor substrate **10** and

11

the second gripper **500**. Here, the supporting the lower support **30** implies suction or blowing performed on the lower support **30**.

The second peeling roll **600** rotates itself to a direction of the second gripper **500**. For example, the second peeling roll **600** delaminates the lower support **30** from the donor film **20** by being rotated to the counterclockwise direction.

Like the first peeling roll **300**, the second peeling roll **600** may include a fixing shaft, an external roll, a barrier, and a cover, and the fixing shaft, the external roll, the barrier, and the cover included in the second peeling roll **600** may be the same as the fixing shaft **310**, the external roll **320**, the barrier **330**, and the cover **340** included in the first peeling roll **300**.

The second support roll **700** may be disposed opposite to the second peeling roll **600**, interposing the lower support **30** therebetween, and the lower support **30** may be supported between the second peeling roll **600** and the second support roll **700** when the lower support **30** may be delaminated from the donor film **20**.

Like the first peeling roll **300**, the second support roll **700** may include a fixing shaft, an external roll, a barrier, and a cover, and the fixing shaft, the external roll, the barrier, and the cover included in the second support roll **700** may be the same as the fixing shaft **310**, the external roll **320**, the barrier **330**, and the cover **340** included in the first peeling roll **300**.

As described, in the delamination apparatus **3004** according to the fourth exemplary embodiment of the present invention, the donor film **20** between the acceptor substrate **10** and the first gripper **200** may be supported between the first peeling roll **300** and the first support roll **400** and thus being delaminated from the lower support **30**, and at the same time, the lower support **30** between the acceptor substrate **10** and the second gripper **500** may be supported between the second peeling roll **600** and the second support roll **700** and thus being delaminated from the donor film **20** so that a failure that may occur in the acceptor substrate **10** due to suction or blowing by the first peeling roll **300**, the first support roll **400**, the second peeling roll **600**, and the second support roll **700** can be originally prevented.

While this invention has been described in connection with what is presently considered to be practical exemplary embodiments, it is to be understood that the invention is not limited to the disclosed embodiments, but, on the contrary, is intended to cover various modifications and equivalent arrangements included within the spirit and scope of the appended claims.

What is claimed is:

1. A delamination apparatus, comprising:

a stage to which a lower support, an acceptor substrate disposed on the lower support, and a donor film laminated with the lower support along the edge of the acceptor substrate, interposing the acceptor substrate therebetween are mounted;

a first gripper disposed in an end side of the stage to move an end of the donor film to a direction away from the acceptor substrate by gripping the end of the donor film; and

a first peeling roll disposed on the donor film to support the donor film disposed between the acceptor substrate and the first gripper, and rotating itself to a direction of the first gripper, the first peeling roll comprises:

a fixing shaft through which air passes, and including a first slit penetrated in the fixing shaft in a geometric plane between the acceptor substrate and the first gripper from the inside of the fixing shaft;

an external roll surrounding the fixing shaft, rotating itself with respect to the fixing shaft, and including a

12

plurality of second slits disposed along an outer part and penetrated to a direction of the fixing shaft; and a barrier supported by the fixing shaft and disposed between the fixing shaft and the external roll, and opening a direction between the acceptor substrate and the first gripper.

2. The delamination apparatus of claim 1, wherein the barrier opens approximately a 1/4 area of an entire outer part of the fixing shaft.

3. The delamination apparatus of claim 1, wherein the air moves from the first slit to the second slit.

4. The delamination apparatus of claim 1, wherein the air moves from the second slit to the first slit.

5. The delamination apparatus of claim 1, wherein the first peeling roll further comprises a cover surrounding the external roll.

6. The delamination apparatus of claim 5, wherein the cover comprises:

a first sub-cover disposed in a location corresponding to the end of the donor film and blocking the second slit;

a second sub-cover disposed adjacent to the first sub-cover in a location corresponding to a portion of the donor film laminated with the lower support, and including a plurality of first penetration holes; and

a third sub-cover disposed adjacent to the second sub-cover in a location corresponding to the acceptor substrate and including a plurality of second penetration holes that are smaller than the first penetration holes in size.

7. The delamination apparatus of claim 1, further comprising first support roll disposed opposite to the first peeling roll, interposing the donor film therebetween.

8. The delamination apparatus of claim 1, further comprising:

a second gripper disposed in an end side of the stage to grip an end of the lower support, and moving the end of the lower support to a direction away from the acceptor substrate; and

a second peeling roll disposed on the lower support to support the lower support disposed between the acceptor substrate and the second gripper, and rotating itself to a direction of the second gripper.

9. The delamination apparatus of claim 8, further comprising a second support roll disposed opposite to the second peeling roll, interposing the lower support therebetween.

10. An inline thermal imaging system, comprising: the delamination apparatus of claim 1;

a transferring apparatus neighboring the delamination apparatus, and including a laser unit irradiating laser beams to the donor film in a location corresponding to the acceptor film;

a lamination apparatus neighboring the transferring apparatus, and including a lamination unit laminating the donor film to the lower support, interposing the acceptor substrate therebetween.

11. The inline thermal imaging system of claim 10, wherein the first peeling roll comprises:

a fixing shaft through which air passes, and including a first slit penetrated to a direction between the acceptor substrate and the first gripper from the inside of the fixing shaft;

an external roll surrounding the fixing shaft, rotating itself with respect to the fixing shaft, and including a plurality of second slits disposed along an outer part and penetrated to a direction of the fixing shaft; and

13

a barrier supported by the fixing shaft and disposed between the fixing shaft and the external roll, and opening a direction between the acceptor substrate and the first gripper.

12. An inline thermal imaging system, comprising;

a delamination apparatus, comprising:

a stage to which a lower support, an acceptor substrate disposed on the lower support, and a donor film laminated with the lower support along the edge of the acceptor substrate, interposing the acceptor substrate therebetween are mounted;

a first gripper disposed in an end side of the stage to move an end of the donor film to a direction away from the acceptor substrate by gripping the end of the donor substrate; and

a first peeling roll disposed on the donor film to support the donor film disposed between the acceptor substrate and the first gripper, and rotating itself to a direction of the first gripper; said inline thermal imaging system, comprising:

a transferring apparatus neighboring the delamination apparatus, and including a laser unit irradiating laser beams to the donor film in a location corresponding to the acceptor film;

a lamination apparatus neighboring the transferring apparatus, and including as lamination unit laminating the donor film to the lower support, interposing the acceptor substrate therebetween; and

a stage movement apparatus respectively moving the stage to the lamination apparatus, the transferring apparatus, and the delamination apparatus, wherein the first peeling roll comprises:

a fixing shaft through which air passes, and including a first slit penetrated to a direction between the acceptor substrate and the first gripper from the inside of the fixing shaft;

an external roll surrounding the fixing shaft, rotating itself with respect to the fixing shaft, and including a plurality of second slits disposed along an outer part and penetrated to a direction of the fixing shaft; and

a barrier supported by the fixing shaft and disposed between the fixing shaft and the external roll, and opening a direction between the acceptor substrate and the first gripper.

14

13. The inline thermal imaging system of claim 12, wherein the barrier opens approximately a 1/4 area of an entire outer part of the fixing shaft.

14. The inline thermal imaging system of claim 12, wherein the air moves from the first slit to the second slit.

15. The inline thermal imaging system of claim 12, wherein the air moves from the second slit to the first slit.

16. The inline thermal imaging system of claim 12, wherein the first peeling roll further comprises a cover surrounding the external roll.

17. The inline thermal imaging system of claim 16, wherein the cover comprises:

a first sub-cover disposed in a location corresponding to the end of the donor film and blocking the second slit;

a second sub-cover disposed adjacent to the first sub-cover in a location corresponding to a portion of the donor film laminated with the lower support, and including a plurality of first penetration holes; and

a third sub-cover disposed adjacent to the second sub-cover in a location corresponding to the acceptor substrate and including a plurality of second penetration holes that are smaller than the first penetration holes in size.

18. The inline thermal imaging system of claim 12 further comprising a first support roll disposed opposite to the first peeling roll, interposing the donor film therebetween.

19. The inline thermal imaging system of claim 12, further comprising:

a second gripper disposed in an end side of the stage to grip an end of the lower support, and moving the end of the lower support to a direction far away from the acceptor substrate; and

a second peeling roll disposed on the lower support to support the lower support disposed between the acceptor substrate and the second gripper, and rotating itself to a direction of the second gripper.

20. The inline thermal imaging system of claim 19, further comprising a second support roll disposed opposite to the second peeling roll, interposing the lower support therebetween.

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